

In re application of:

Liming Tsau

Appl. No.: 10/750,834

Filed: January 5, 2004

For: High Density Metal Capacitor

Using Via Etch Stopping Layer as Field Dielectric in Dual-

Damascence Interconnect Process

Confirmation No.: 2507

Art Unit: 2823

Examiner: Khiem D. Nguyen

Atty. Docket: 1875.0230001

Request for Corrected Official Filing Receipt

Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

10Xundi1a, V11 22313-1

Attn: Office of Initial Patent
Examination's Filing
Receipt Corrections

Sir:

Applicant hereby requests that a corrected Official Filing Receipt be issued and sent to the undersigned representative. Specifically, the following corrections to the Official Filing Receipt are requested: Under "Power of Attorney" delete Keith Aurzada -- 43477 and insert "The patent practitioners associated with Customer Number 49579". In support of the above request, a photocopy of the instant Official Filing Receipt is enclosed with the corrections noted in red. It is requested that a corrected Official Filing Receipt be issued, and sent to the undersigned at the earliest possible time.

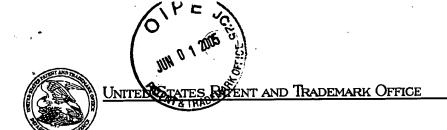
Respectfully submitted,

STERNE, KESSLER, GOLØSTEIN & FOX P.L.L.C.

Jason D. Eisenberg Attorney for Applicant Registration No. 43,447

Date:

1100 New York Avenue, N.W. Washington, D.C. 20005-3934 (202) 371-2600



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FILING OR 371 APPL NO. (c) DATE

ART UNIT

FIL FEE REC'D

ATTY.DOCKET NO

DRAWINGS

TOT CLMS IND CLMS

10/750,834 01/05/2004

26111

2823

STERNE, KESSLER, GOLDSTEIN & FOX PLLC

1100 NEW YORK AVENUE, N.W.

WASHINGTON, DC 20005

770

1875.0230001

CONFIRMATION NO. 2507

UPDATED FILING RECEIPT

OC000000013679380*

Date Mailed: 09/03/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Liming Tsau, Irvine, CA;

Assignment For Published Patent Application

Broadcom Corporation

Power of Attorney:

-Keith-Aurzada-12477- The patent practitioners associa With Customer number 49579.

Domestic Priority data as claimed by applicant

This application is a CON of 09/753,664 01/04/2001

Foreign Applications

If Required, Foreign Filing License Granted: 04/08/2004

The number of your priority application, to be used for filing abroad under the Paris Convention is, US10/750.834

Projected Publication Date: 12/09/2004

Non-Publication Request: No

Early Publication Request: No

STERNE, KESSLER

Title

High density metal capacitor using via etch stopping layer as field dielectric in dual-damascence interconnect process

Preliminary Class

438

LICENSE FOR FOREIGN FILING UNDER Title 35, United States Code, Section 184 Title 37, Code of Federal Regulations, 5.11 & 5.15

GRANTED

The applicant has been granted a license under 35 U.S.C. 184, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" followed by a date appears on this form. Such licenses are issued in all applications where the conditions for issuance of a license have been met, regardless of whether or not a license may be required as set forth in 37 CFR 5.15. The scope and limitations of this license are set forth in 37 CFR 5.15(a) unless an earlier license has been issued under 37 CFR 5.15(b). The license is subject to revocation upon written notification. The date indicated is the effective date of the license, unless an earlier license of similar scope has been granted under 37 CFR 5.13 or 5.14.

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NOT GRANTED

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June 1, 2005

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*Admitted only in Maryland *Admitted only in Virginia *Practice Limited to Federal Agencies

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Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450 Art Unit 2823
Office of Initial Patent Examination's
Filing Receipt Corrections

Re:

U.S. Utility Patent Application

Application No. 10/750,834; Filed: January 5, 2004

For: High Density Metal Capacitor Using Via Etch Stopping Layer as

Field Dielectric in Dual-Damascence Interconnect Process

Inventor:

Liming Tsau

Our Ref:

1875.0230001

Sir:

Transmitted herewith for appropriate action are the following documents:

- 1. Request for Corrected Official Filing Receipt;
- 2. A photocopy of the Official Filing Receipt with corrections noted in red;
- 3. A Supplemental Application Data Sheet;
- 4. An original executed Power of From Assignee;
- 5. A copy of the Statement Under 37 C.F.R. 3.73(b) as filed in U.S. Appl. No. 09/753,664, with copy of Assignment attached; and
- 6. One (1) return postcard.

It is respectfully requested that the attached postcard be stamped with the date of filing of these documents, and that it be returned to our courier. In the event that extensions of time are necessary to prevent abandonment of this patent application, then such extensions of time are hereby petitioned.

Sterne, Kessler, Goldstein & Fox PLLC.: 1100 New York Avenue, NW: Washington, DC 20005: 202.371.2600 f202.371.2540: www.skaf.com

Commissioner for Patents June 1, 2005 Page 2

The U.S. Patent and Trademark Office is hereby authorized to charge any fee deficiency, or credit any overpayment, to our Deposit Account No. 19-0036.

Respectfully submitted,

STERNE, KESSLER, GOLDSTEIN & FOX P.L.L.C.

Jason D. Eisenberg Attorney for Applicant

Registration No. 43,447

 $\underset{\texttt{402625_1.DOC}}{\textbf{JDE/lvt}}$

SUPPLEMENTAL APPLICATION DATA SHEET

Electronic Version v14 Stylesheet Version v14.0

> Title of Invention

High Density Metal Capacitor Using Via Etch Stopping Layer as Field

Dielectric in Dual-Damascence Interconnect Process

Application Type:

regular, utility

Attorney Docket Number: 1875.0230001/JDE

Correspondence address:

Customer Number:

26111

26111

Continuing Data:

This is a Continuation of US application number 09/753,664, filed 2001-01-04.

Inventor Information:

<u>Inventor 1</u>:

Applicant Authority Type:

Inventor

Citizenship:

CN

Given Name:

Liming

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Attorney Information:		
Name	Registration Number	
Jason D. Eisenberg	43.477 43.447	

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POWER OF ATTORNEY FROM ASSIGNEE

Broadcom Corporation, a corporation of California, having a principal place of business at 16215 Alton Parkway, Irvine, California 92618-3616, is assignee of the entire right, title and interest for the United States of America (as defined in 35 U.S.C. § 100), by reason of an Assignment to the Assignee executed on December 29, 2000, of an invention known as High Density Metal Capacitor Using Via Etch Stopping Layer as Field Dielectric in Dual-Damascence Interconnect Process (Attorney Docket No. 1875.0230001), that is disclosed and claimed in a patent application of the same title by the inventor Liming Tsau (said application filed on January 5, 2004 at the U.S. Patent and Trademark Office, having Application Number 10/750,834).

For the purpose of PAIR, the Customer Number is 26111.

The Assignee hereby appoints the U.S. attorneys associated with CUSTOMER NUMBER 49579 to prosecute this application and any continuation, divisional, continuation-in-part, or reissue application thereof, and to transact all business in the U.S. Patent and Trademark Office connected therewith. The Assignee hereby grants said attorneys associated with Customer Number 49579 the power to insert on this Power of Attorney any further identification that may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office.

Send correspondence to:

Customer Number 26111
STERNE, KESSLER, GOLDSTEIN & FOX P.L.L.C.
1100 New York Avenue, N.W.
Washington, D.C. 20005-3934
U.S.A.

Direct phone calls to 202-371-2600.

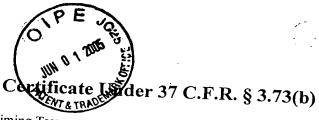
OR: Broadcom Corporation

SIGNATURE:_

BY: Dee Henderson

TITLE: Senior Manager, Intellectual Property Administration

DATE: May 19, 2005



Арриса	tion No./Patent No.: 09/753,664 Filed/Issue Date: January 4, 2001	
Entitled:	High Density Metal Capacitor Using Via Etch Stopping Layer as Field Dielectric in Dual-	
	Broadcom Corporation , a corporation (Name of Assignee) (Type of Assignee)	
	(*) pe of Assignee, e.g., corporation, partnership, university, conversity, co	
states tha	t it is:	,
	he assignee of the entire right, title, and interest, or	
2. [] a	in assignee of an undivided part interest	
in the pate	ent application/patent identified above by virtue of either:	
A. [X] A w th	on Assignment from the inventor(s) of the patent application/patent identified above. The assignment are recorded in the Patent and Trademark Office at Reel <u>011420</u> , Frame <u>0610</u> , or for which a copperent is attached.	nt y
B.[] A	chain of title from the inventor(s) of the patent application/patent identified above to the current signee as shown below:	
	From: To: To: The document was recorded in the Patent and Trademark Office at Reel, Frame, or for which a copy thereof is attached. From: To: To: The document was recorded in the Patent and Trademark Office at	
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3.]	From: To: To:	
	and document was recorded in the Document and the	
	or for which a copy thereof is attached	
[]	Additional documents in the chain of title are listed on a supplemental sheet	
J Copies o	f assignments or other documents in the state of the stat	
doc	<u>PTE:</u> A separate copy (i.e., the original assignment document or a true copy of the original assignment) must be submitted to Assignment Division in accordance with the original	
the a	iment) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if assignment is to be recorded in the records of the PTO. See MPEP 302-302.8	
e undersig	ned (whose title is supplied below) is empowered to act on behalf of the assignee.	
te:	April 13, 2001	
ne: Wil	liam Ruehle	
e: Vi	ce President & CFO	
nature:	Martin	

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration paid to each of the undersigned inventor: <u>Liming Tsau</u>, the undersigned inventor hereby sell and assign to <u>Broadcom Corporation</u> (the Assignee) his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present and future damages:

check applicable box(es)

✓ for the United States of America (as defined in 35 U.S.C. § 100),

✓ and throughout the world,

(a) in the invention known as <u>High Density Metal Capacitor Using Via Etch Stopping Layer as Field Dielectric in Dual-Damascence Interconnect Process</u> for which application for patent in the United States of America has been executed by the undersigned on <u>Pec. 29, 2000</u> (also known as United States Application No. to be assigned, filed herewith), in any and all applications thereon, in any and all Letters Patent(s) therefor, and

Sve 1/4/01

- (b) in any and all applications that claim the benefit of the patent application listed above in part (a), including continuing applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefor listed above in part (a), to the full extent of the term or terms for which Letters Patents issue, and
- (c) in any and all inventions described in the patent application listed above in part (a), and in any and all forms of intellectual and industrial property protection derivable from such patent application, and that are derivable from any and all continuing applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefor; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The undersigned inventor(s) agree(s) to execute all papers necessary in connection with the application(s) and any continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s) thereof and also to execute separate assignments in connection with such application(s) as the Assignee may deem necessary or expedient.

The undersigned inventor(s) agree(s) to execute all papers necessary in connection with any interference or patent enforcement action (judicial or otherwise) related to the application(s) or any continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application(s) thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference or patent enforcement action.

The undersigned inventor(s) hereby represent(s) that he/she has full right to convey the entire interest herein assigned, and that he/she has not executed, and will not execute, any agreement in conflict therewith.

The undersigned inventor(s) hereby grant(s) Robert Greene Sterne, Esquire, Registration No. 28,912; Edward J. Kessler, Esquire, Registration No. 25,688; Jorge A. Goldstein, Esquire, Registration No. 29,021; Samuel L. Fox, Esquire, Registration No. 30,353; David K.S. Cornwell, Esquire, Registration No. 31,944; Robert W. Esmond, Esquire, Registration No. 32,893; Tracy-Gene G. Durkin, Esquire, Registration No. 32,831; Michael A. Cimbala, Esquire, Registration No. 33,851; Michael B. Ray, Esquire, Registration No. 33,997; Robert E. Sokohl,

Esquire, Registration No. 36,013; Eric K. Steffe, Esquire, Registration No. 36,688; Michael Q. Lee, Esquire, Registration No. 35,239; Steven R. Ludwig, Esquire, Registration No. 36,203; John M. Covert, Esquire, Registration No. 38,759; and Linda E. Alcorn, Esquire, Registration No. 39,588; all of STERNE, KESSLER, GOLDSTEIN & FOX P.L.L.C., 1100 New York Avenue, N.W., Suite 600, Washington, D.C. 20005-3934, power to insert in this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREOF, executed by the undersigned inventor(s) on the date opposite his/her name.

Date: 12/29/2006

Signature of Inventor:

Liming Tsau